

### FEATURES

- Double Side Cooling
- High Surge Capability

### KEY PARAMETERS

$V_{RRM}$	<b>1800V</b>
$I_{F(AV)}$	<b>2996A</b>
$I_{FSM}$	<b>41250A</b>

### VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages $V_{RRM}$ V	Conditions
DRD2460F18 DRD2460F16 DRD2460F14	1800 1600 1400	$V_{RSM} = V_{RRM} + 100V$

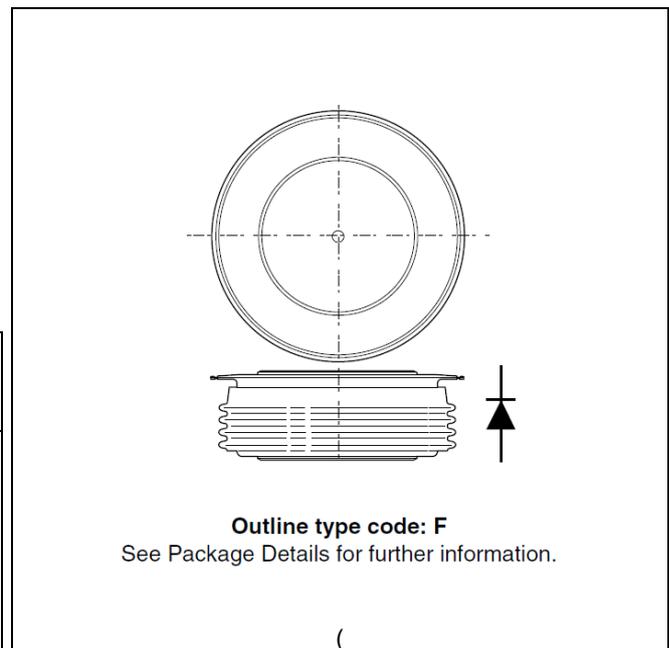


Fig. 1 Package outline

### ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

**DRD2460F14** for a 1400V device

**CURRENT RATINGS**

$T_{case} = 75^{\circ}C$  unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
<b>Double Side Cooled</b>				
$I_{F(AV)}$	Mean forward current	Half wave resistive load	2996	A
$I_{F(RMS)}$	RMS value	-	4707	A
$I_F$	Continuous (direct) on-state current	-	4122	A
<b>Single Side Cooled (Anode side)</b>				
$I_{F(AV)}$	Mean forward current	Half wave resistive load	2093	A
$I_{F(RMS)}$	RMS value	-	3288	A
$I_F$	Continuous (direct) on-state current	-	2693	A

$T_{case} = 100^{\circ}C$  unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
<b>Double Side Cooled</b>				
$I_{F(AV)}$	Mean forward current	Half wave resistive load	2460	A
$I_{F(RMS)}$	RMS value	-	3856	A
$I_F$	Continuous (direct) on-state current	-	3310	A
<b>Single Side Cooled (Anode side)</b>				
$I_{F(AV)}$	Mean forward current	Half wave resistive load	1693	A
$I_{F(RMS)}$	RMS value	-	2659	A
$I_F$	Continuous (direct) on-state current	-	2128	A

**SURGE RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
$I_{FSM}$	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 175^{\circ}C$ $V_R = 50\% V_{RRM} - 1/4$ sine	33.0	kA
$I^2t$	$I^2t$ for fusing		5.44	MA <sup>2</sup> s
$I_{FSM}$	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 175^{\circ}C$ $V_R = 0$	41.25	kA
$I^2t$	$I^2t$ for fusing		8.5	MA <sup>2</sup> s

**THERMAL AND MECHANICAL RATINGS**

Symbol	Parameter	Test Conditions	Min.	Max.	Units	
$R_{th(j-c)}$	Thermal resistance – junction to case	Double side cooled	DC	-	0.022	$^{\circ}C/W$
		Single side cooled	Anode DC	-	0.038	$^{\circ}C/W$
			Cathode DC	-	0.052	$^{\circ}C/W$
$R_{th(c-h)}$	Thermal resistance – case to heatsink	Clamping force 43kN (with mounting compound)	Double side	-	0.004	$^{\circ}C/W$
			Single side	-	0.008	$^{\circ}C/W$
$T_{vj}$	Virtual junction temperature	On-state (conducting)	-	185	$^{\circ}C$	
		Reverse (blocking)	-	175	$^{\circ}C$	
$T_{stg}$	Storage temperature range		-55	200	$^{\circ}C$	
$F_m$	Clamping force		18.0	22.0	kN	

CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V <sub>FM</sub>	Forward voltage	At 3400A peak, T <sub>case</sub> = 25°C	-	1.18	V
I <sub>RM</sub>	Peak reverse current	At V <sub>RRM</sub> , T <sub>case</sub> = 175°C	-	50	mA
Q <sub>S</sub>	Total stored charge	I <sub>F</sub> = 2000A, dI <sub>RR</sub> /dt = 3A/μs	-	1500	μC
I <sub>rr</sub>	Peak reverse recovery current	T <sub>case</sub> = 175°C, V <sub>R</sub> = 100V	-	90	A
V <sub>TO</sub>	Threshold voltage	At T <sub>vj</sub> = 175°C	-	0.74	V
r <sub>T</sub>	Slope resistance	At T <sub>vj</sub> = 175°C	-	0.088	mΩ

CURVES

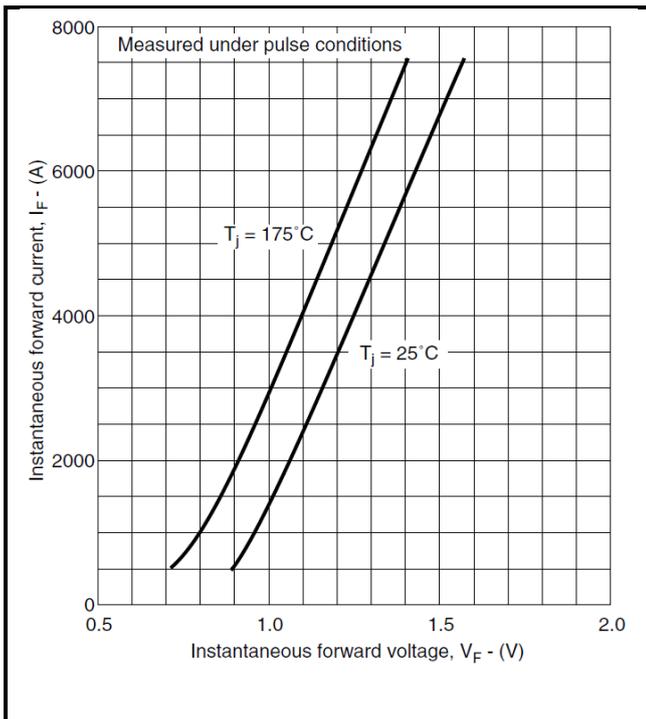


Fig.2 Maximum & minimum on-state characteristics

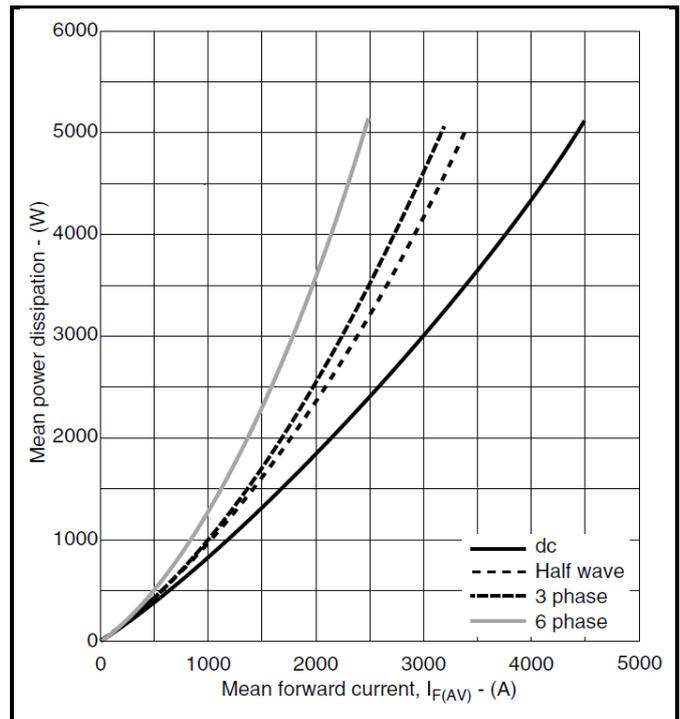


Fig.3 Dissipation curves

V<sub>TM</sub> EQUATION

$$V_{TM} = A + B \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

Where A = -0.64773  
 B = 0.268581  
 C = 0.00016  
 D = -0.01796

these values are valid for T<sub>j</sub> = 175°C for I<sub>F</sub> (AV) to 8000A

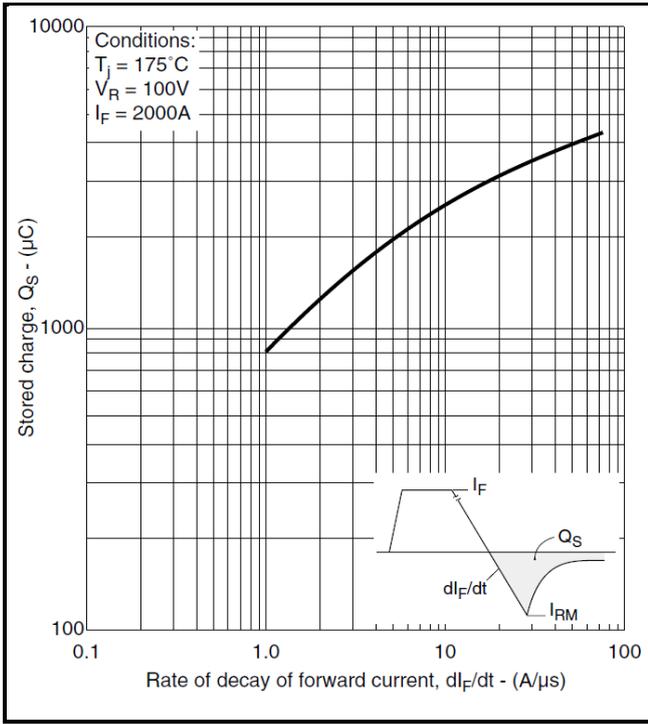


Fig.4 Total stored charge

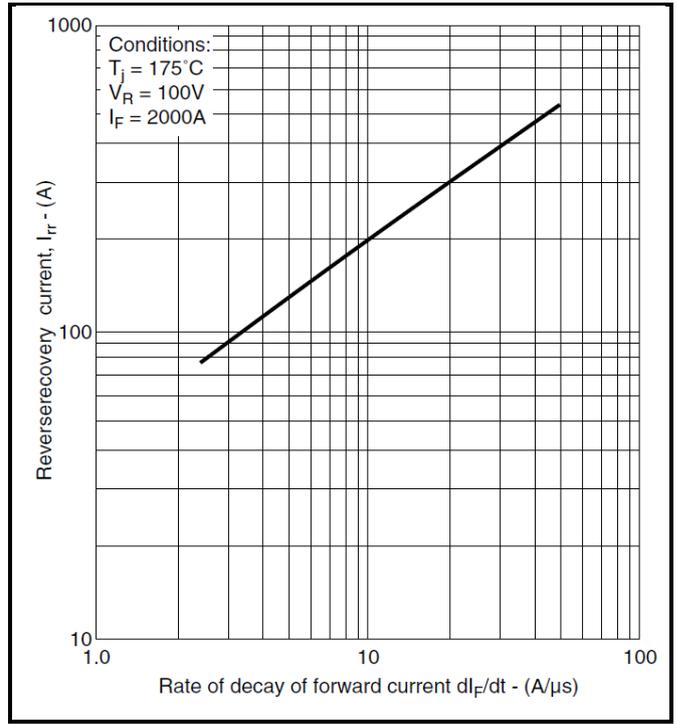


Fig.5 Maximum reverse recovery current

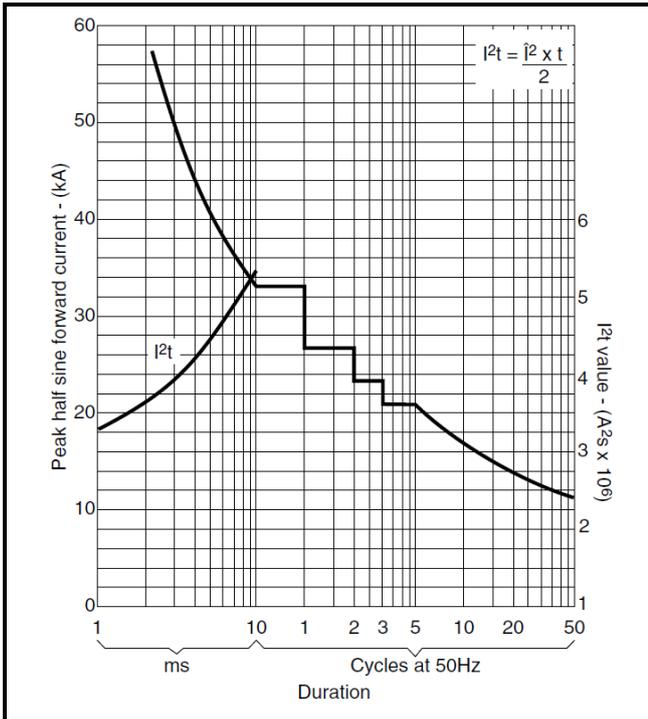


Fig.5 Surge (Non-Repetitive) Forward current vs time

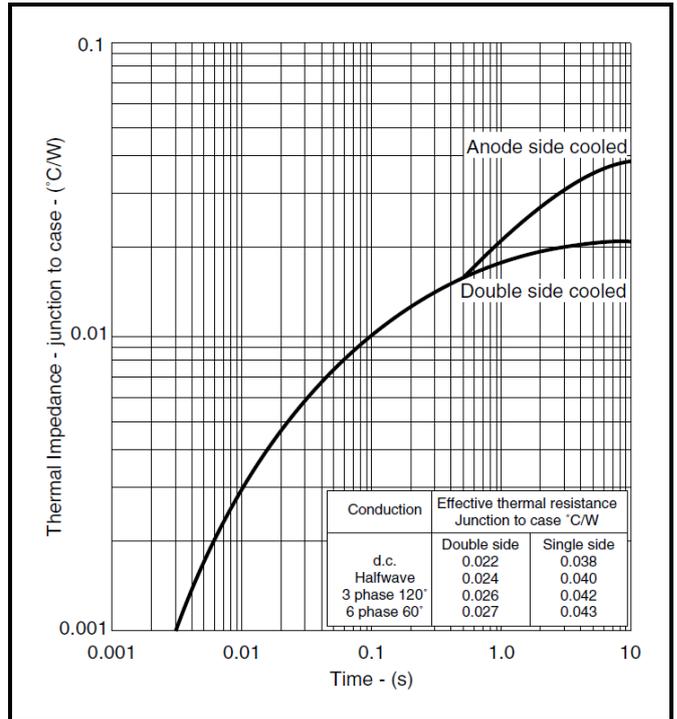
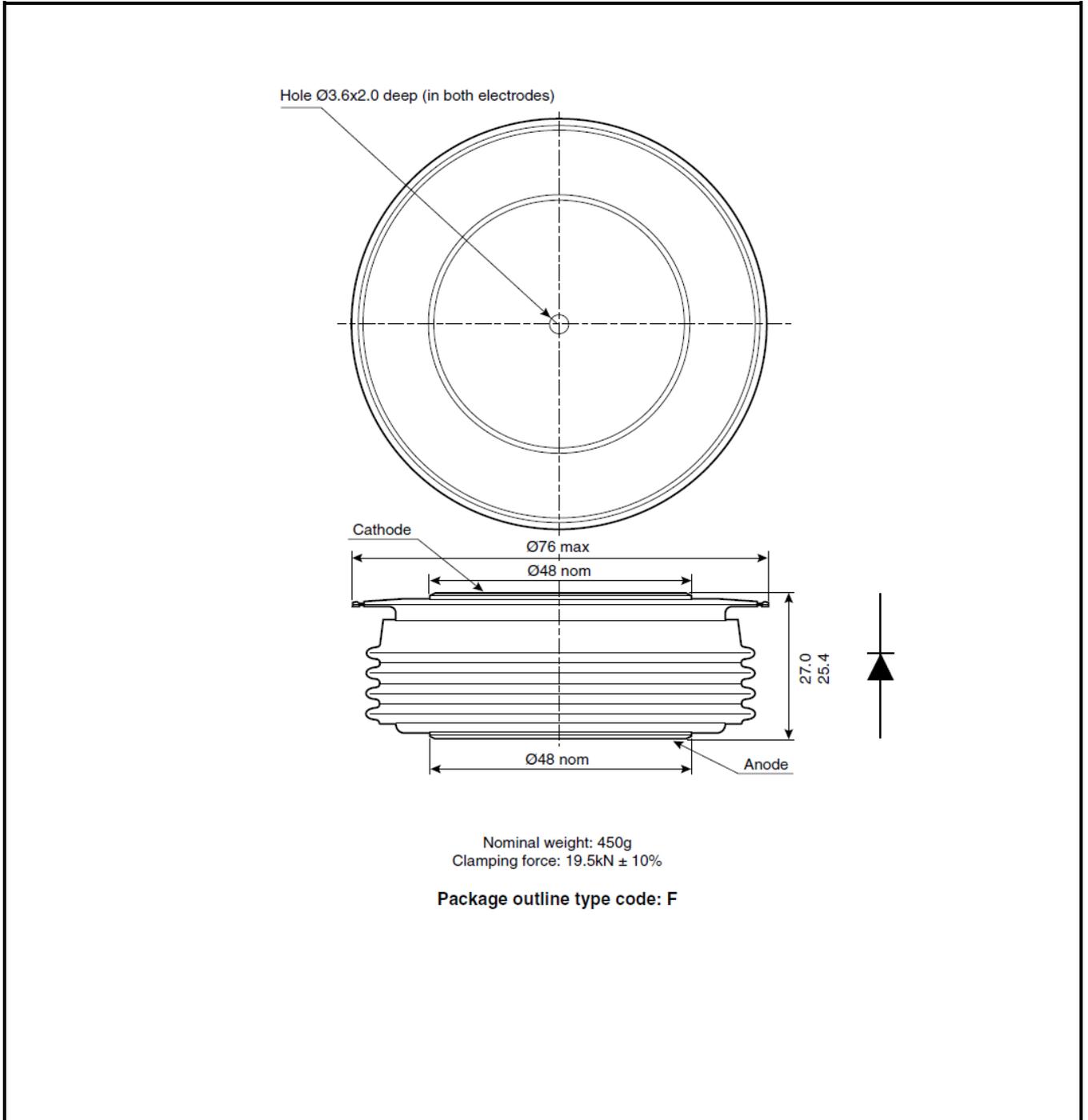


Fig.7 Maximum (limit) transient thermal impedance-junction to case

PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



**Note:**  
Some packages may be supplied with gate and or tags.

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